

**NEWS RELEASE**

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**SEMICON China to Feature Demonstrations of Latest Wafer-Like Processing Metrology Sensors From CyberOptics Semiconductor**

**WaferSense® Sensors at Booth 3437 Hosted by Distribution Partner Scientech**

SHANGHAI and WILSONVILLE, Ore., March 3, 2010 - Engineers at fabs in China preparing to bear a load of the world's resurgent chip demand will be able to demonstrate at SEMICON China the latest wafer-like sensors from Oregon-based CyberOptics Semiconductor to optimize fab-wide processes and maintain processing equipment.

Demonstrations of the company's wireless WaferSense® sensors in Shanghai come at a time when fabs throughout China "really need to stretch yield as a recently contracted supply chain catches up with demand," said Ferris Chen, director of Asia for CyberOptics Semiconductor, a subsidiary of CyberOptics Corp. (Nasdaq:CYBE).

"We've seen that manual methods to measure processing parameters at fabs in China are a barrier to automation and productivity," Chen said. "And many production challenges at fabs related to downtime and defects can be linked to equipment calibration."

Each WaferSense device follows the processing life of a wafer across the fab and reports real-time metrology data via a GUI. Engineers use the precise measurements obtained with the sensors to establish yield-based tolerances and controls for fab processes and technicians.

Chen said that data from fabs indicate that the company's 300 mm and 200 mm form factor carbon-fiber sensors help engineers to "routinely reduce equipment downtime and total cost of ownership."

"Fabs in Asia have used our devices for a number of applications -- within each process -- and we're always learning more about how they're being used," Chen said.

Engineers implement CyberOptics' WaferSense sensors to optimize equipment and tools used to perform processes across the fab: photolithography; etch; diffusion; thin film; implant; metallization; chemical mechanical planarization (CMP) and fab automation.

CyberOptics Semiconductor's WaferSense metrology sensors will be demonstrated at booth 3437, which will be hosted by its distribution partner, Scientech.

The WaferSense family of devices includes the Auto Vibration System (AVS), Auto Leveling System (ALS2), Auto Teaching System (ATS), Auto Gapping System (AGS) and Airborne Particle Sensor (APS).

For more information on the WaferSense line, visit <http://www.cyberopticssemi.com/products/wafersense/>

## **About CyberOptics Semiconductor, Inc.**

CyberOptics Semiconductor develops automated products that seamlessly measure critical parameters in semiconductor fabrication processes and equipment. The company's pioneering WaferSense® line includes wireless metrology devices for vibration, leveling, gapping, teaching and sensing airborne particles in semiconductor process equipment. The company is the largest producer of [reflective wafer-mapping sensors](#) and a leading provider of [frame grabber machine vision boards](#) under its HAMA Sensors™ and Imagenation™ brands. CyberOptics Semiconductor is a subsidiary of CyberOptics Corp. (Nasdaq:CYBE), one of the world's leading providers of process yield and throughput improvement solutions for the electronic assembly and semiconductor fabrication industries. For information, visit <http://www.cyberopticssemi.com/>, e-mail CSsales@cyberoptics.com or call 800-366-9131.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; the impact of current economic conditions on the Company's performance; the timing and magnitude of any potential recovery in financial performance resulting from the global economic downturn; the need for a valuation allowance with respect to our deferred tax assets; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required for meeting customer orders; the effect of world events on our sales, the majority of which are from foreign customers; product introductions and pricing by our competitors; the timing of and our ultimate ability to return to profitability in 2010; success of anticipated new OEM and end user opportunities and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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